

FIG.*1A*

$$\begin{array}{c} & & & \\ & &$$

FIG.1*B*

$$FIG. 2A$$

Air AC vED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

FIG. 2B

WHERE
$$R = -CH_3$$
 $-CH_2CH_3$
 $-CH_2CH_2CH_3$
 $-CH_2CH_2CH_2CH_3$
 $-C(CH_3)_3$
 $-CH_2CH_2CH_2CH_3$
 $-CH_3$
 $-$

2 thiophenyl

or thiopheny l

FIG. 2C

I. Before CMP, with slurry, Flow on the water where &> = new additive

II. During CMP, due to the formation of the protective film, removal rate becomes different with R1>R2∼R3

Ⅲ. After CMP, the Cu surface is protected by the passive film

FIG. 3

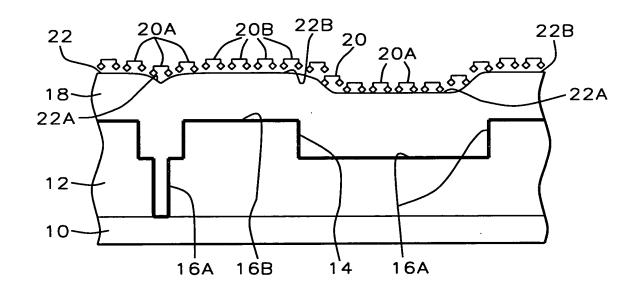


FIG. 4A

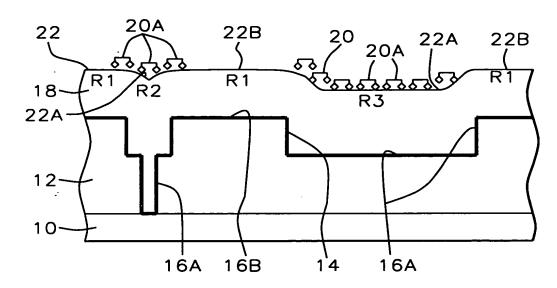


FIG. 4B

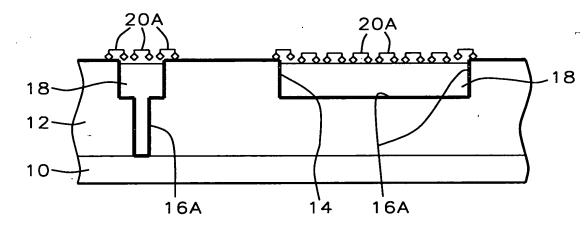


FIG. 4C

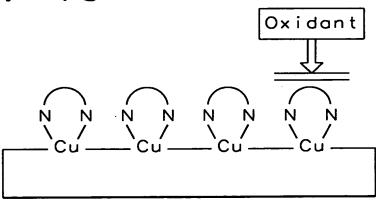


FIG. 5